

Rochester Electronics Manufactured Components

Rochester branded components are manufactured using either die/wafers purchased from the original suppliers or Rochester wafers recreated from the original IP. All recreations are done with the approval of the OCM.

Parts are tested using original factory test programs or Rochester developed test solutions to guarantee product meets or exceed the OCM data sheet.

Quality Overview

- ISO-9001
- AS9120 certification
- Qualified Manufacturers List (QML) MIL-PRF-35835
 - Class Q Military
 - Class V Space Level
- Qualified Suppliers List of Distributors (QSLD)
- Rochester is a critical supplier to DLA and meets all industry and DLA standards.

Rochester Electronics, LLC is committed to supplying products that satisfy customer expectations for quality and are equal to those originally supplied by industry manufacturers.

The original manufacturer's datasheet accompanying this document reflects the performance and specifications of the Rochester manufactured version of this device. Rochester Electronics guarantees the performance of its semiconductor products to the original OEM specifications. 'Typical' values are for reference purposes only. Certain minimum or maximum ratings may be based on product characterization, design, simulation, or sample testing.

Dual 1-of-4 Decoder/ Demultiplexer

The LSTTL/MSI SN74LS139 is a high speed Dual 1-of-4 Decoder/Demultiplexer. The device has two independent decoders, each accepting two inputs and providing four mutually exclusive active LOW Outputs. Each decoder has an active LOW Enable input which can be used as a data input for a 4-output demultiplexer. Each half of the LS139 can be used as a function generator providing all four minterms of two variables. The LS139 is fabricated with the Schottky barrier diode process for high speed and is completely compatible with all ON Semiconductor TTL families.

- Schottky Process for High Speed
- Multifunction Capability
- Two Completely Independent 1-of-4 Decoders
- Active Low Mutually Exclusive Outputs
- Input Clamp Diodes Limit High Speed Termination Effects
- ESD > 3500 Volts

GUARANTEED OPERATING RANGES

Symbol	Parameter	Min	Тур	Max	Unit
V _{CC}	Supply Voltage	4.75	5.0	5.25	V
T _A	Operating Ambient Temperature Range	0	25	70	ပို
I _{OH}	Output Current - High			-0.4	mA
I _{OL}	Output Current - Low			8.0	mA



ON Semiconductor™

http://onsemi.com

LOW POWER SCHOTTKY



PLASTIC N SUFFIX CASE 648



SOIC D SUFFIX CASE 751B



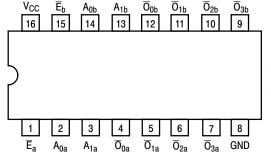
SOEIAJ M SUFFIX CASE 966

ORDERING INFORMATION

Device	Package	Shipping	
SN74LS139N	16 Pin DIP	2000 Units/Box	
SN74LS139D	SOIC-16	38 Units/Rail	
SN74LS139DR2	SOIC-16	2500/Tape & Reel	
SN74LS139M	SOEIAJ-16	See Note 1	
SN74LS139MEL	SOEIAJ-16	See Note 1	

For ordering information on the EIAJ version of the SOIC package, please contact your local ON Semiconductor representative.

CONNECTION DIAGRAM DIP (TOP VIEW)



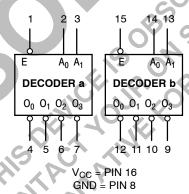
NOTE:

The Flatpak version has the same pinouts (Connection Diagram) as the Dual In-Line Package.

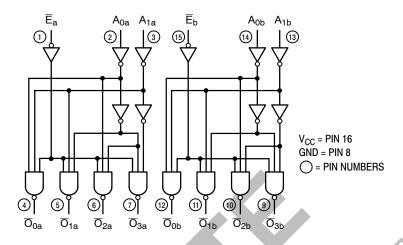
NOTES:

a) 1 TTL Unit Load (U.L.) = 40 µA HIGH/1.6 mA LOW.

LOGIC SYMBOL



LOGIC DIAGRAM



FUNCTIONAL DESCRIPTION

The LS139 is a high speed dual 1-of-4 decoder/demultiplexer fabricated with the Schottky barrier diode process. The device has two independent decoders, each of which accept two binary weighted inputs (A_0, A_1) and provide four mutually exclusive active LOW outputs $(\overline{O}_0-\overline{O}_3)$. Each decoder has an active LOW Enable (\overline{E}) . When E is HIGH all outputs are forced HIGH. The enable

can be used as the data input for a 4-output demultiplexer application.

Each half of the LS139 generates all four minterms of two variables. These four minterms are useful in some applications, replacing multiple gate functions as shown in Fig. a, and thereby reducing the number of packages required in a logic network.

TRUTH TABLE

INPUTS				OUTPUTS
E	A ₀	A ₁	\overline{O}_0	\overline{O}_1 \overline{O}_2 \overline{O}_3
Н	Х	X	Н	н н н
L	L	L	L	H H HC
L	Н	L	Н	L H H
L	L	Н	Н	H L H
L	Н	Н	Н	H H L

H = HIGH Voltage Level

L = LOW Voltage Level

X = Don't Care

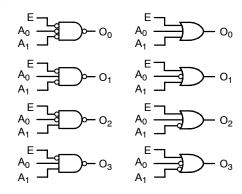


Figure a

DC CHARACTERISTICS OVER OPERATING TEMPERATURE RANGE (unless otherwise specified)

			Limits				
Symbol	Parameter	Min	Тур	Max	Unit	Tes	t Conditions
V _{IH}	Input HIGH Voltage	2.0			٧	Guaranteed Input HIGH Voltage for All Inputs	
V _{IL}	Input LOW Voltage			0.8	V	Guaranteed Input LOW Voltage for All Inputs	
V _{IK}	Input Clamp Diode Voltage		-0.65	-1.5	V	V _{CC} = MIN, I _{IN} = -18 mA	
V _{OH}	Output HIGH Voltage	2.7	3.5		V	V_{CC} = MIN, I_{OH} = MAX, V_{IN} = V_{IH} or V_{IL} per Truth Table	
	0.15.11.00//////		0.25	0.4	V		V _{CC} = V _{CC} MIN,
V_{OL}	Output LOW Voltage		0.35	0.5	V	I _{OL} = 8.0 mA	V _{IN} = V _{IL} or V _{IH} per Truth Table
1	lanut IIICI Current			20	μΑ	V _{CC} = MAX, V _{IN}	= 2.7 V
I _{IH}	Input HIGH Current			0.1	mA	V _{CC} = MAX, V _{IN} = 7.0 V	
I _{IL}	Input LOW Current			-0.4	mA	V _{CC} = MAX, V _{IN} = 0.4 V	
I _{OS}	Short Circuit Current (Note 2)	-20		-100	mA	V _{CC} = MAX	
I _{CC}	Power Supply Current			11	mA	V _{CC} = MAX	

^{2.} Not more than one output should be shorted at a time, nor for more than 1 second.

AC CHARACTERISTICS (T_A = 25°C)

		Levels of	Lim	its	.0	
Symbol	Parameter	Delay	Min Ty	р Мах	Unit	Test Conditions
t _{PLH} t _{PHL}	Propagation Delay Address to Output	2 2	22		ns	
t _{PLH} t _{PHL}	Propagation Delay Address to Output	3 3	18 25		ns	$V_{CC} = 5.0 V$ $C_L = 15 pF$
t _{PLH} t _{PHL}	Propagation Delay Enable to Output	2 2) 16 21		ns	

AC WAVEFORMS

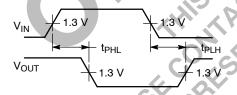


Figure 1.

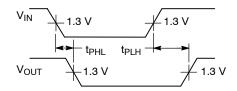
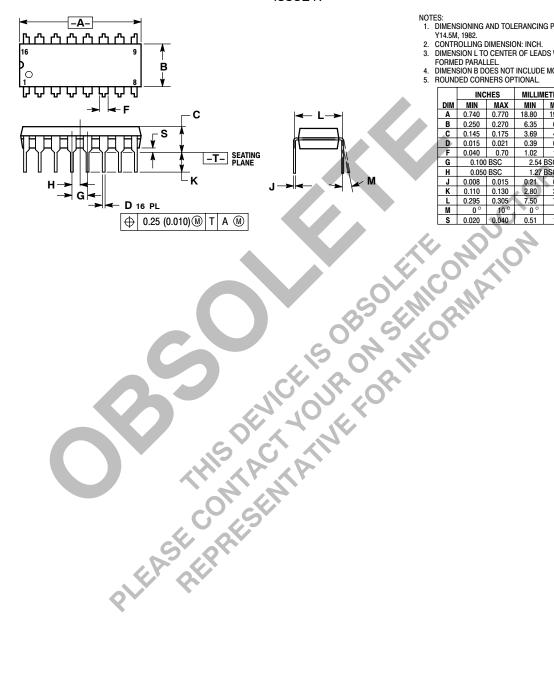


Figure 2.

PACKAGE DIMENSIONS

N SUFFIX PLASTIC PACKAGE CASE 648-08 **ISSUE R**



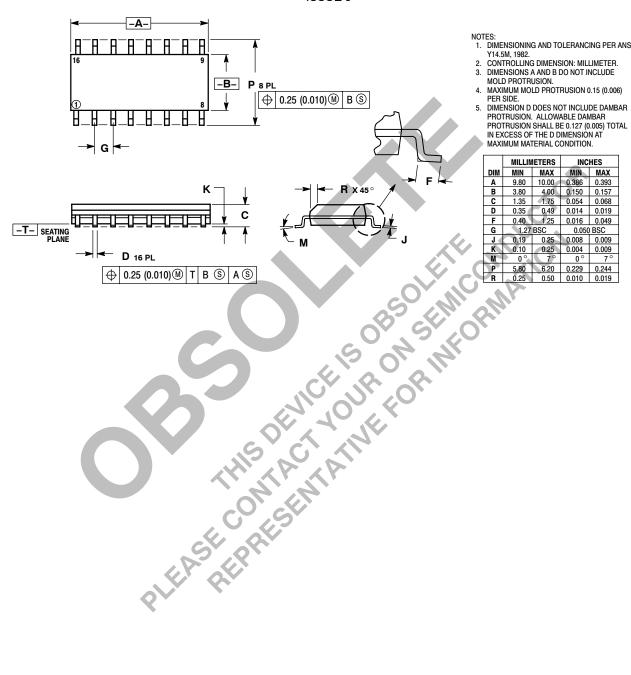
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI
 - Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- DIMENSION L TO CENTER OF LEADS WHEN
- FORMED PARALLEL.
 DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 ROUNDED CORNERS OPTIONAL.

		INC	HES	MILLIN	IETERS	
	DIM	MIN	MAX	MIN	MAX	
	Α	0.740	0.770	18.80	19.55	
	В	0.250	0.270	6.35	6.85	
	Ç	0.145	0.175	3.69	4.44	
4	Ê	0.015	0.021	0.39	0.53	
ı	F	0.040	0.70	1.02	1.77	
1	G	0.100	BSC	2.54 BSC		
	Н	0.050	BSC	1.27 BSC		
	7	0.008	0.015	0.21	0.38	
	K	0.110	0.130	2.80	3.30	
	L	0.295	0.305	7.50	7.74	
	M	0°	10°	0 °	10 °	
	S	0.020	0.040	0.51	1.01	

PACKAGE DIMENSIONS

D SUFFIX

PLASTIC SOIC PACKAGE CASE 751B-05 **ISSUE J**



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

- Y14.5M, 1982.

 CONTROLLING DIMENSION: MILLIMETER.

 DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.

 MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.

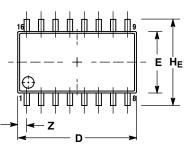
 DIMENSION D DOES NOT INCLUDE DAMBAR DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

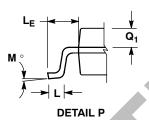
	MILLIM	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
A	9.80	10.00	0.386	0.393	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.054	0.068	
D	0.35	0.49	0.014	0.019	
F	0.40	1.25	0.016	0.049	
G	1.27	BSC	0.050 BSC		
J	0.19	0.25	0.008	0.009	
K	0.10	0.25	0.004	0.009	
M	0°	7°	0°	7°	
P	5.80	6.20	0.229	0.244	
Ь	0.25	0.50	0.010	0.010	

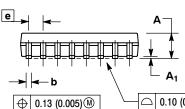
PACKAGE DIMENSIONS

M SUFFIX

SOEIAJ PACKAGE CASE 966-01 ISSUE O









NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETER
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- 4. TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.

 5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α		2.05	-1	0.081	
Α1	0.05	0.20	0.002	0.008	
b	0.35	0.50	0.014	0.020	
C	0.18	0.27	0.007	0.011	
D	9.90	10.50	0.390	0.413	
E	5.10	5.45	0.201	0.215	
e	1.27	BSC	0.050	BSC	
ΗE	7.40	8.20	0.291	0.323	
L	0.50	0.85	0.020	0.033	
LΕ	1.10	1.50	0.043	0.059	
M	0 °	10°	0 °	10°	
Q ₁	0.70	0.90	0.028	0.035	
Z		0.78		0.031	

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